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Substitute for form 1449APTO	Complete if Known	required to respond to a collection of information unless it contains a valid OMB control number
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	<b>Application Number</b>	Unknown 10/789-028
Use as many sheels as necessary)	Filing Date	Even Date Herewith 02-27-04
	First Named Inventor	Forbes, Leonard
	Group Art Unit	Unknown 2827
	Examiner Name	Pham, Ly
Sheet 1 of 5	Attorney Docket No: 1	1303.024US2

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Application Number	Unknown 10/784.038			
	Filing Date	Even Date Herewith 02-27-04			
	First Named Inventor	Forbes, Leonard			
	Group Art Unit	Unknown 2827			
	Examiner Name	Pham, Ly			
Sheet 3 of 5	Attorney Docket No:	1303.024US2			

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Application Number	Unknown 10/789,038				
(Use as many sheets as necessary)	Filing Date	Even Date Herewith 02-27-04				
	First Named Inventor	Forbes, Leonard				
	Group Art Unit	Unknown 2827				
	Examiner Name	Pham, Ly				
Sheet 4 of 5	Attorney Docket No:	1303.024US2				

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Application Number	Unknown 10/784, 038
(Use as many sheets as necessary)	Filing Date	Even Date Herewith -02-27-04
	First Named Inventor	Forbes, Leonard
	Group Art Unit	-Unknown 2827
	Examiner Name	Pham, Ly
Sheet 5 of 5	Attorney Docket No: 1	1303.024US2

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Application Number 10/789,038

Filing Date February 27, 2004

First Named Inventor Forbes, Leonard

Group Art Unit 2817 2827

Examiner Name Pham, Ly

Attorney Docket No: 1303.024US2

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nder the Paparvork Reduction Act of 1995, no persons are required to respond to a o Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE **Application Number** 10/789,038 STATEMENT BY APPLICANT February 27, 2004 Filing Date Forbes, Leonard First Named Inventor 281T **Group Art Unit Examiner Name** Pham, Ly Attorney Docket No: 1303.024US2

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Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE 10/789,038 **Application Number** STATEMENT BY APPLICANT (Use as many sheets as necessary) Filing Date February 27, 2004 Forbes, Leonard **First Named Inventor Group Art Unit** 2827 <u>AUG</u> 0 5 2005 **Examiner Name** Pham, Ly Attorney Docket No: 1303.024US2 Sheet 1 of 1

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Sheet 1 of 1

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INEORMATION DISCLOSURE Complete If Known 10/789,038 **Application Number** TEMENT BY APPLICANT Filing Date February 27, 2004 Forbes, Leonard **First Named Inventor Group Art Unit** 2827 Pham, Ly **Examiner Name** Attorney Docket No: 1303.024US2

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OTHER DOCUMENTS - NON PATENT LITERATURE DOCUMENTS				
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**EXAMINER** 

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